

Environmental testing - Part 2-69: Tests - Test Te/Tc:
Solderability testing of electronic components and
printed boards by the wetting balance (force
measurement) method

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN 60068-2-69:2017 sisaldab Euroopa standardi EN 60068-2-69:2017 ingliskeelset teksti.	This Estonian standard EVS-EN 60068-2-69:2017 consists of the English text of the European standard EN 60068-2-69:2017.
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English Version

Environmental testing -
Part 2-69: Tests - Test Te/Tc: Solderability testing of electronic
components and printed boards by the wetting balance (force
measurement) method
(IEC 60068-2-69:2017)

Essais d'environnement -
Partie 2-69: Essais - Essai Te/Tc: Essai de brasabilité des
composants électroniques et cartes imprimées par la
méthode de la balance de mouillage (mesure de la force)
(IEC 60068-2-69:2017)

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Te/TC: Prüfung der Lötbarkeit von Bauelementen der
Elektronik und Leiterplatten mit der Benetzungswaage
(Kraftmessung)
(IEC 60068-2-69:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

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This document supersedes EN 60068-2-69:2007 and EN 60068-2-54:2006.

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-3-13:2016	NOTE	Harmonized as EN 60068-3-13:2016 (not modified).
IEC 61190-1-1:2002	NOTE	Harmonized as EN 61190-1-1:2002 (not modified).
ISO 9453:2014	NOTE	Harmonized as EN ISO 9453:2014 (not modified).

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60068-2-66	-	Environmental testing - Part 2-66: Test methods - Test Cx: Damp heat, steady state (unsaturated pressurized vapour)	EN 60068-2-66	-
IEC 61190-1-3	2007	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2007
+A1	2010		+A1	2010
ISO 683	Series	Heat treatable steels, alloy steels and free-cutting steels	EN ISO 683	Series ¹⁾
ISO 6362	Series	Wrought aluminium and aluminium alloys extruded rods/bars, tubes and profiles	-	-

¹⁾ At draft stage.

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